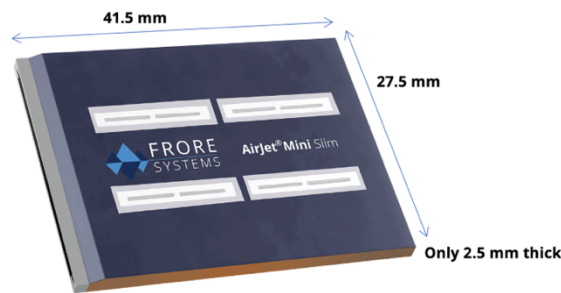


Consumer device performance continues to soar with launch of AirJet® Mini Slim.

Introducing a slimmer, smarter, AirJet® chip for increased performance even in the thinnest electronic devices!



LAS VEGAS, Nevada – January 8, 2024 – At CES2024, Frore Systems, the pioneering developer of AirJet Mini, the world's first Solid-State Active Cooling Chip, unveiled the AirJet Mini Slim - a thinner, lighter, smarter and even more advanced solid-state active cooling chip.

Building on the success of the original AirJet Mini, which garnered widespread recognition, including the prestigious COMPUTEX2023 Golden Award and CES2024 “Best of Innovation” Award, Frore Systems continues to accelerate the pace of innovation in thermal management.

The AirJet® Mini Slim, featuring the same groundbreaking solid-state active cooling design of its predecessor, includes three new features, while remaining silent, lightweight and delivering superior heat removal compared to traditional fans.

WHAT'S NEW

Thinner Design:

At an incredibly thin 2.5mm and weighing only 8g, the AirJet Mini Slim trims an additional 0.3mm from the thickness and 1g from the weight of the original AirJet Mini, while maintaining the same heat removal capability. This ultra-thin profile opens up new possibilities for manufacturers catering to consumer demand for higher performance in increasingly thinner devices. The AirJet Mini Slim is an ideal solution for ultra-thin products like fanless laptops, professional tablets, handheld gaming devices, SSD accessories and smartphones.

Intelligent Self-Cleaning:

Addressing an industry-wide challenge, the AirJet Mini Slim introduces intelligent self-cleaning feature to conquer dust. Dust accumulation has traditionally posed operational risks and decreased performance in electronic devices. The new AirJet Mini Slim tackles this concern with its self-cleaning function that automatically reverses airflow and clears any accumulated dust from the AirJet dust filters. This ensures sustained peak performance of AirJet over the

long term and maintains the high performance of the host device. This intelligent self-cleaning feature is backward compatible and is also available with the AirJet Mini.

Thermoception:

The AirJet Mini Slim introduces Thermoception, a capability that enables AirJet to independently sense its temperature. This innovation allows the AirJet Mini Slim to optimize its performance autonomously, maximizing heat removal without relying on temperature sensors in the host device, opening new possibilities for cooling devices that lack integrated CPUs and temperature sensing components.

Dr. Seshu Madhavapeddy, Founder and CEO of Frore Systems commented on the AirJet Mini Slim, stating, "Reducing the chip's thickness by 0.3mm is a game-changer for products requiring excellent thermal management in increasingly thinner devices. AirJet Mini Slim will bring much-needed performance improvements to ultra-thin electronic devices like fanless laptops, tablets, and smartphones."

Frore Systems launched AirJet in January 2023 and has seen unprecedented demand for the small, highly effective active cooling chips. The latest product, AirJet Mini Slim with its new intelligent capabilities, is just 2.5mm thick and 8g, 0.3mm thinner and 1g lighter than the original AirJet Mini, while retaining the same tiny footprint, just 27.5mm x 41.5mm. Like all Frore System products, AirJet Mini Slim is a scalable solution, with additional heat removal achievable by simply adding more AirJet chips. Each chip removes 5W of heat, and the easy integration of multiple chips means two chips can remove 10W, three chips 15W and so on.

AirJet's compact size and scalable nature means manufacturers can achieve enhanced heat removal for increased performance in a wide range of faster, thinner, lighter, silent, and dustproof devices. AirJet can enhance performance across numerous devices from Notebooks, Mini-PCs, tablets, smartphones and SSDs to the approaching tsunami of IOT devices; DSLR cameras, WiFi access points and LED lighting, and in markets as diverse as the datacenter and automotive industries.

ABOUT FRORE SYSTEMS

Frore Systems is the developer of breakthrough thermal technology for electronic and consumer devices. The company's active cooling chip, AirJet® is integrated into devices to remove heat silently, resulting in major performance gains. Frore Systems is headquartered in San Jose, CA with an office and manufacturing facility in Taiwan. For more information, visit: <https://froresystems.com/>

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